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Moncayo

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(54) **ELECTRICAL INTERFACE FOR PRINTED CIRCUIT BOARD, PACKAGE AND DIE**

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H01L 23/00 (2006.01)
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H05K 1/18 (2006.01)

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(58) **Field of Classification Search**
CPC H05K 1/0246; H05K 1/111–1/116; H05K 1/181; H05K 1/0215–1/0224
See application file for complete search history.

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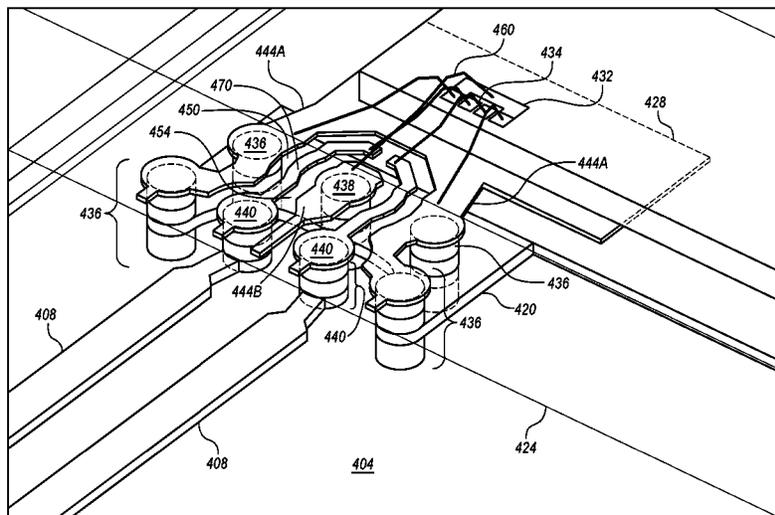
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(57) **ABSTRACT**

A circuit board and package assembly electrically connecting a die to a circuit board. The circuit board has signal paths terminating in a signal pad located on an insulating layer. The circuit board also includes a ground pad on the insulating layer that has a concave shaped side forming a recess, the with a signal pad at least partially within the recess. A package has package ground pads aligned with the circuit board ground pads and package signal pads aligned with circuit board signal pads. The package ground pads extend through the package to connect to package ground paths, which extend toward the die. The package signal pads extend through the package to connect to package signal paths and the package signal paths extend toward the die, maintaining a consistent distance from the package ground paths. Multiple-tier bond wires connect the package bond locations to the die bond pads.

20 Claims, 12 Drawing Sheets



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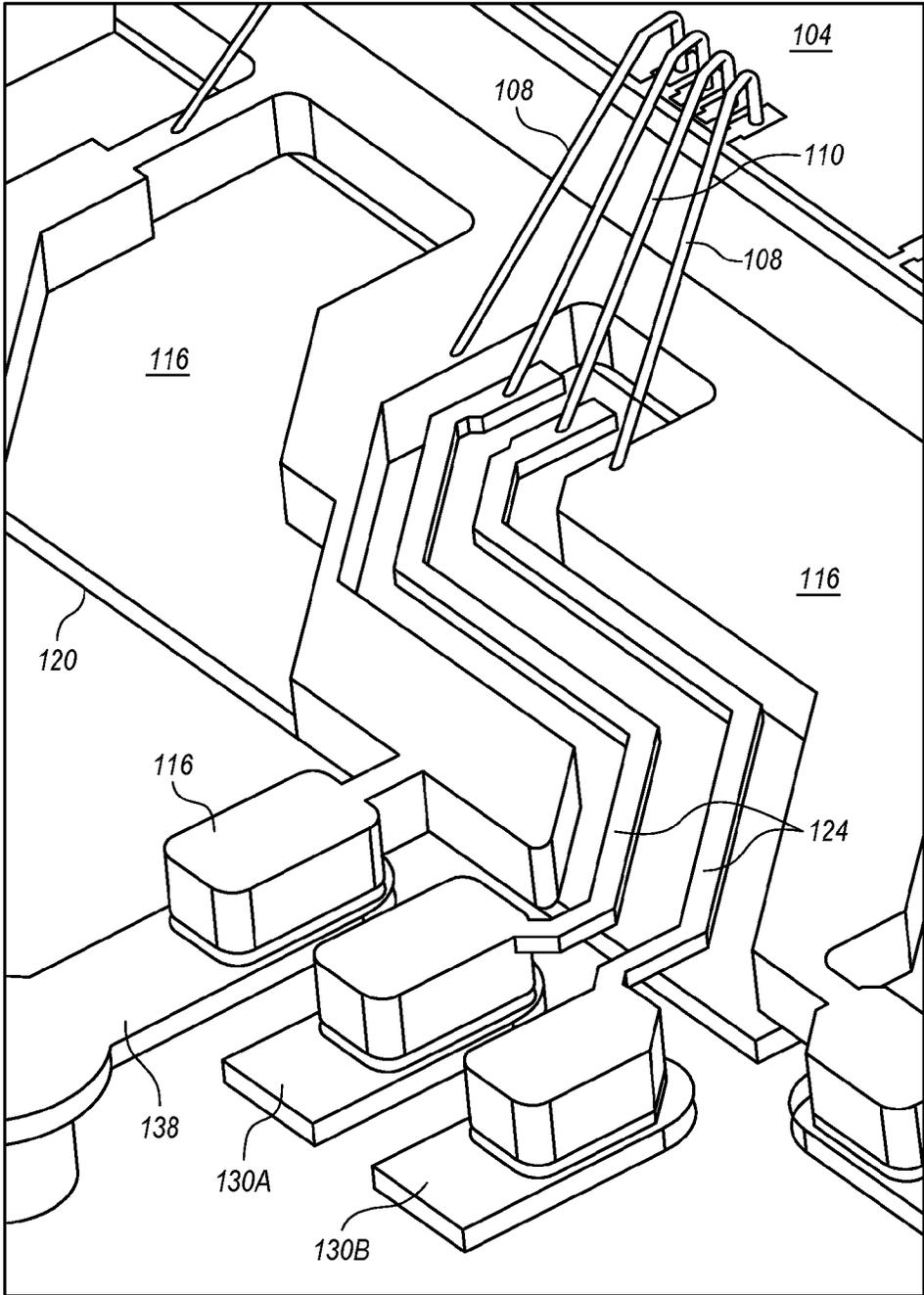


FIG. 1
Prior Art

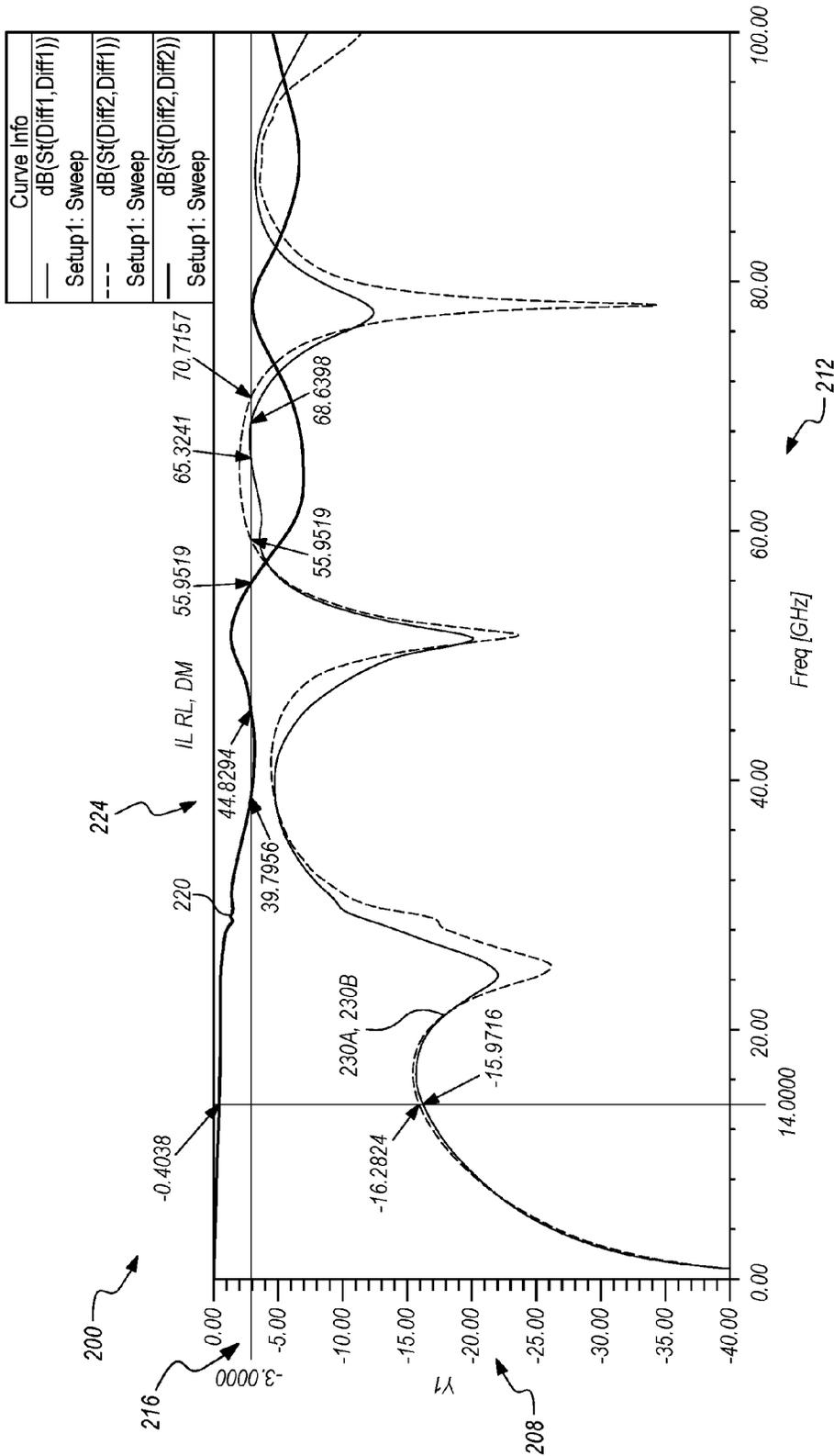


FIG. 2A
Prior Art

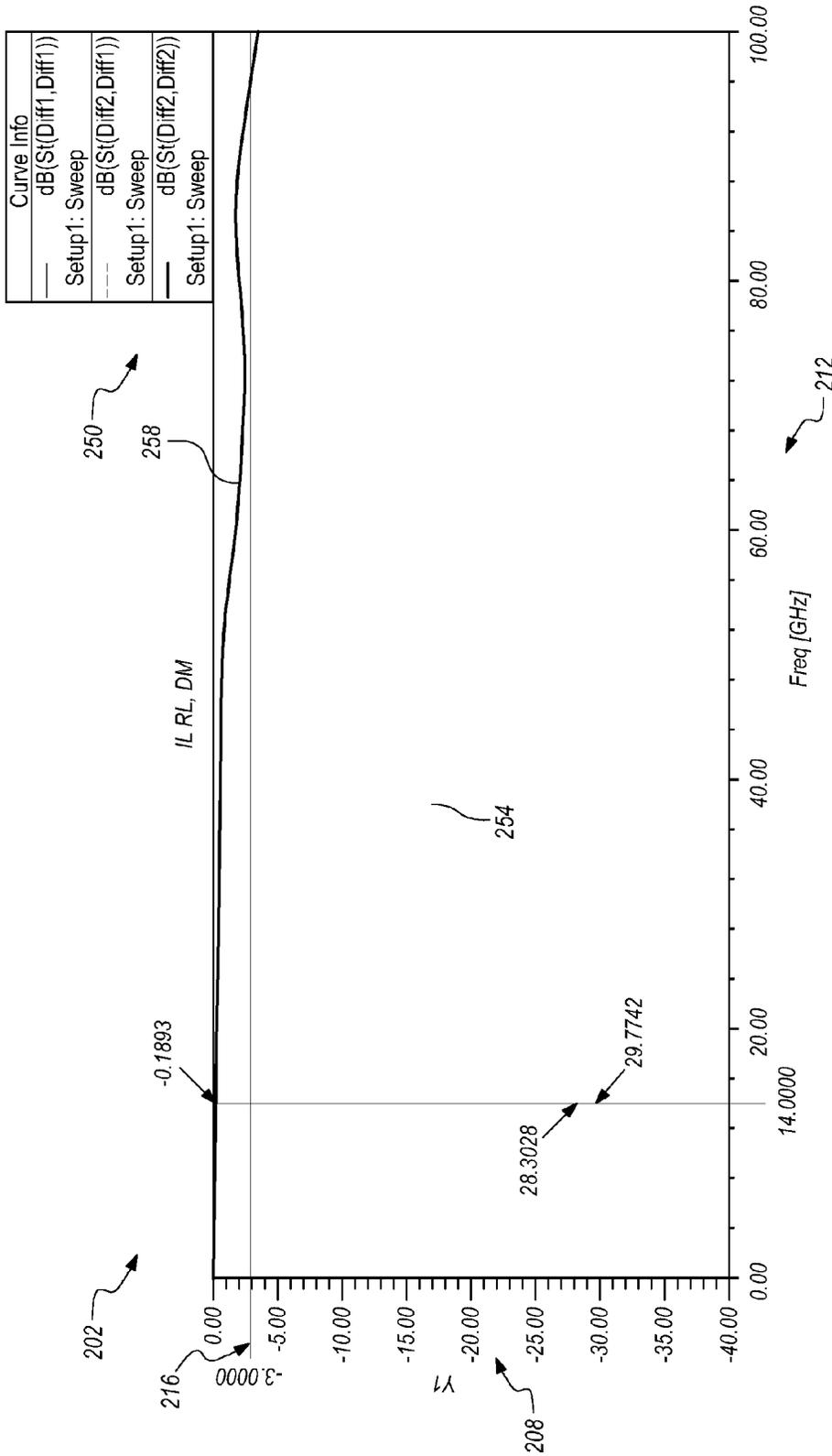


FIG. 2B

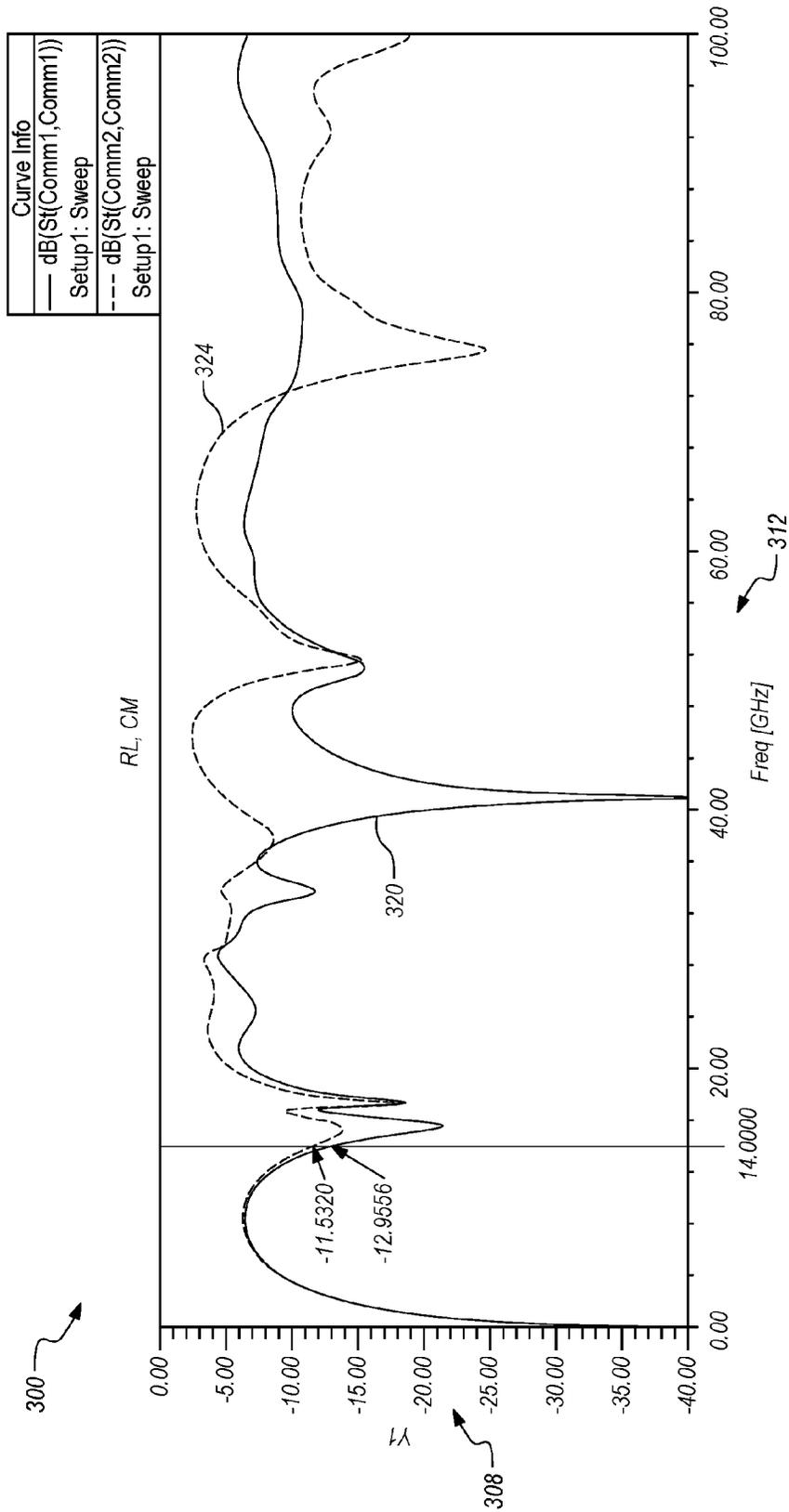


FIG. 3A
Prior Art

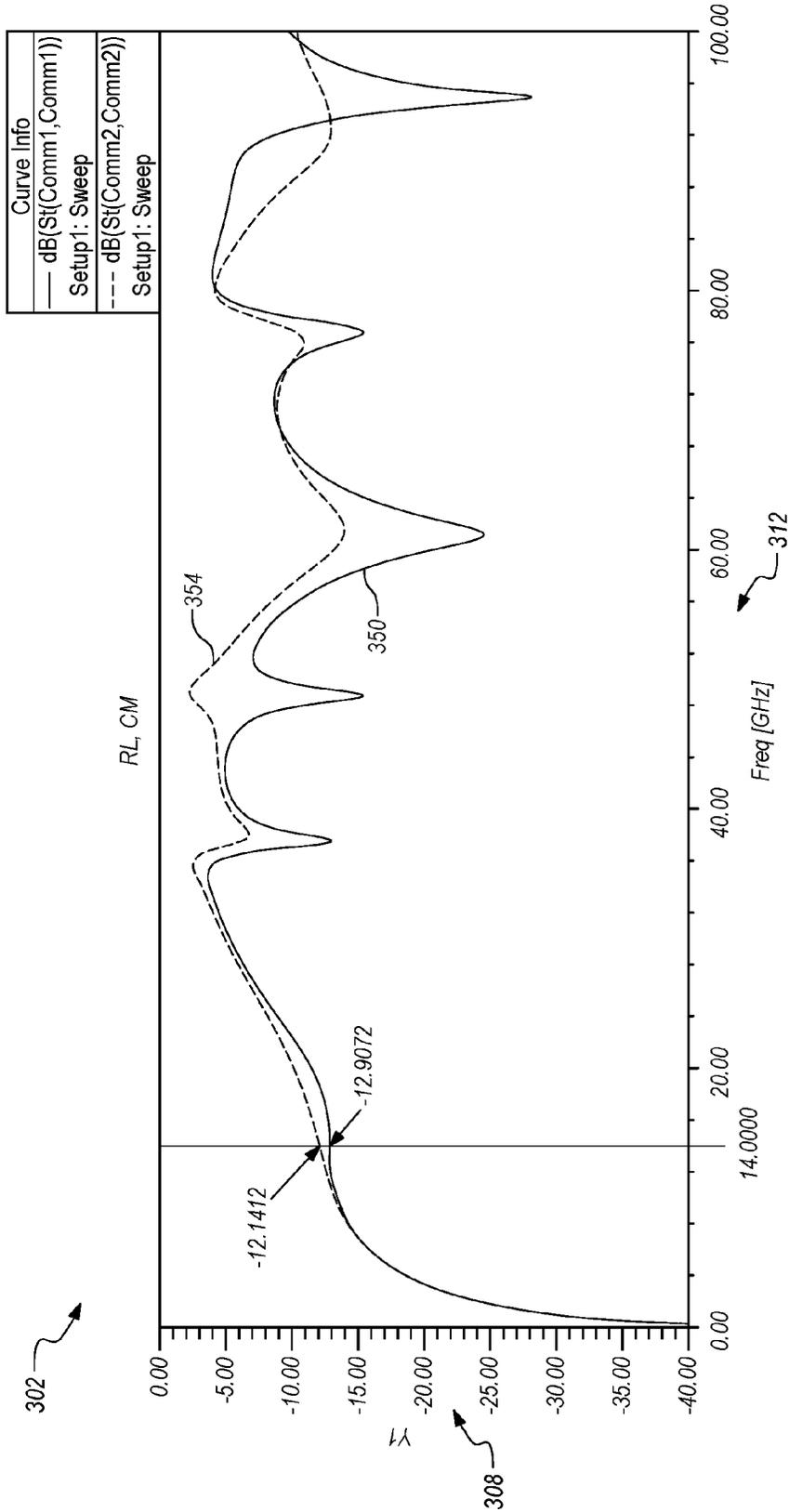


FIG. 3B

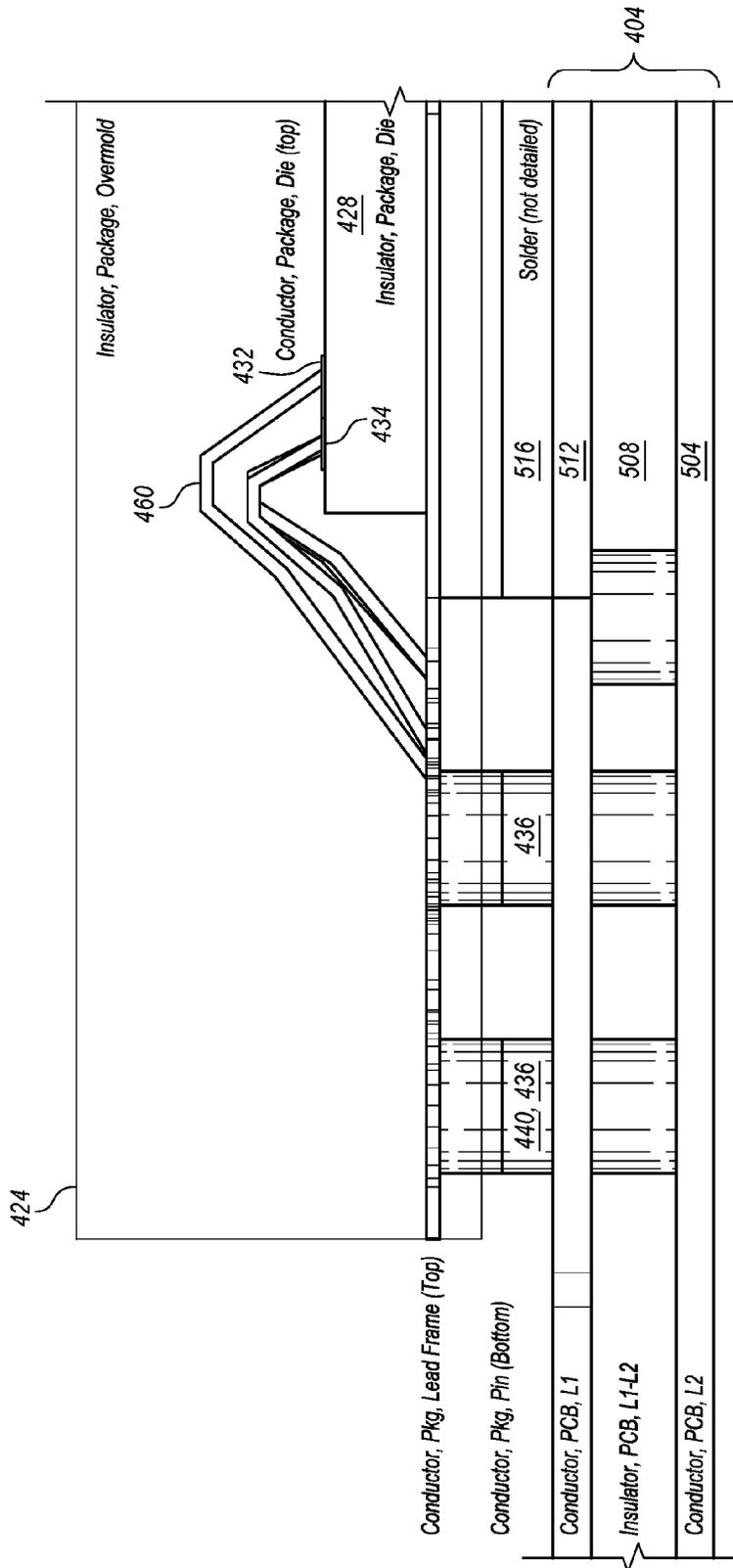


FIG. 5

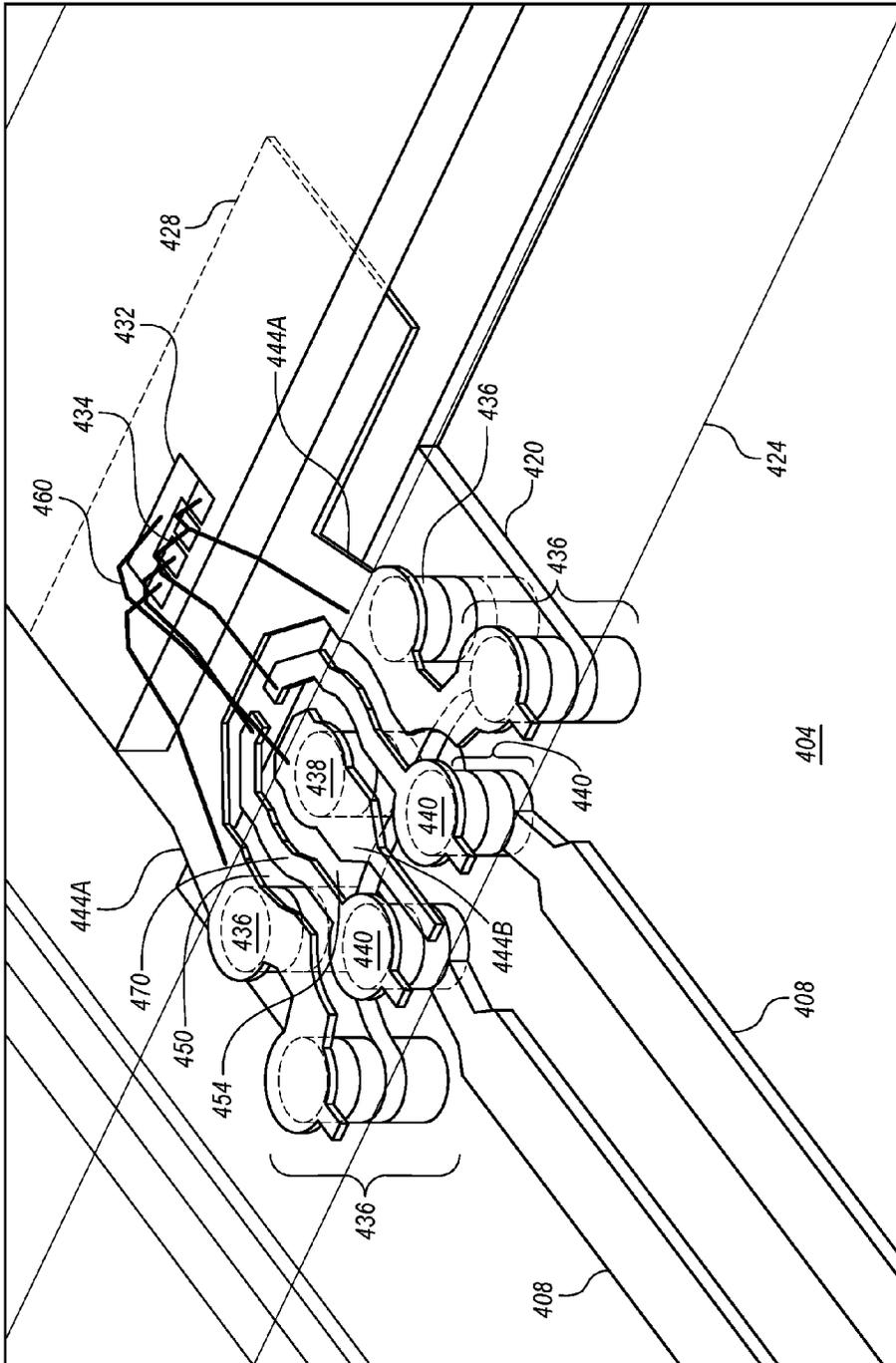


FIG. 6

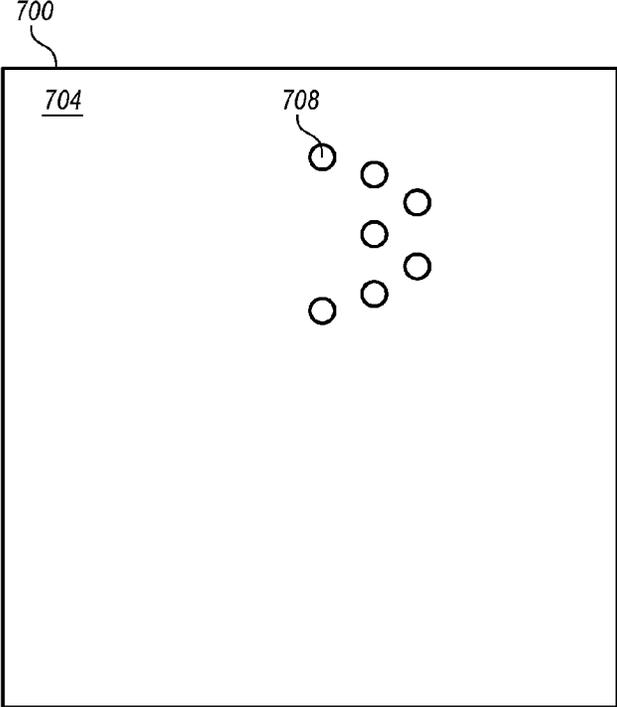


FIG. 7A

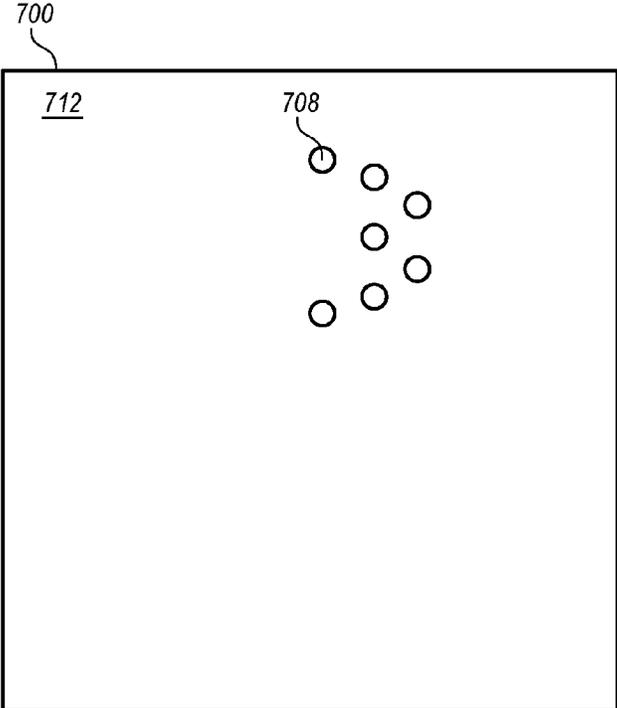


FIG. 7B

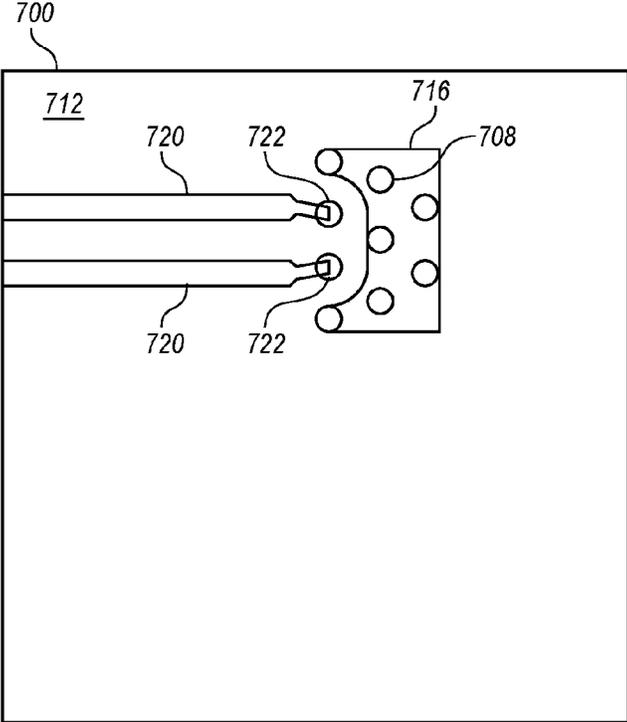


FIG. 7C

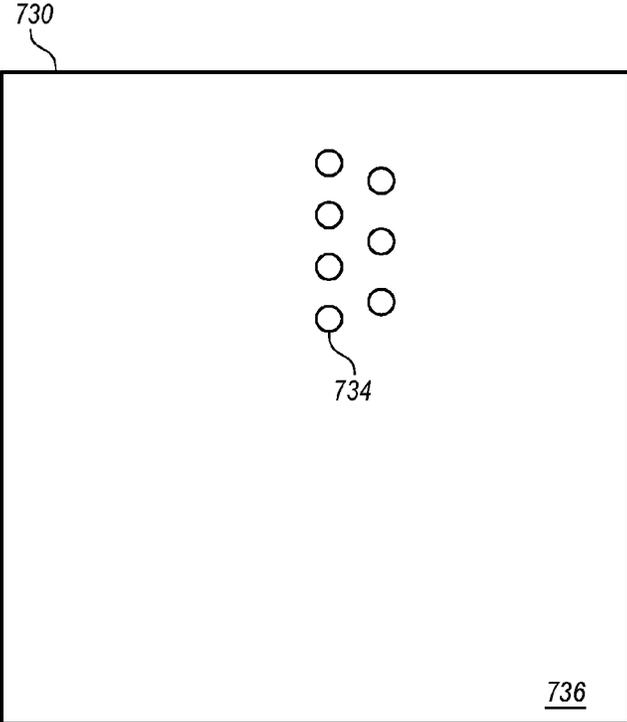


FIG. 7D

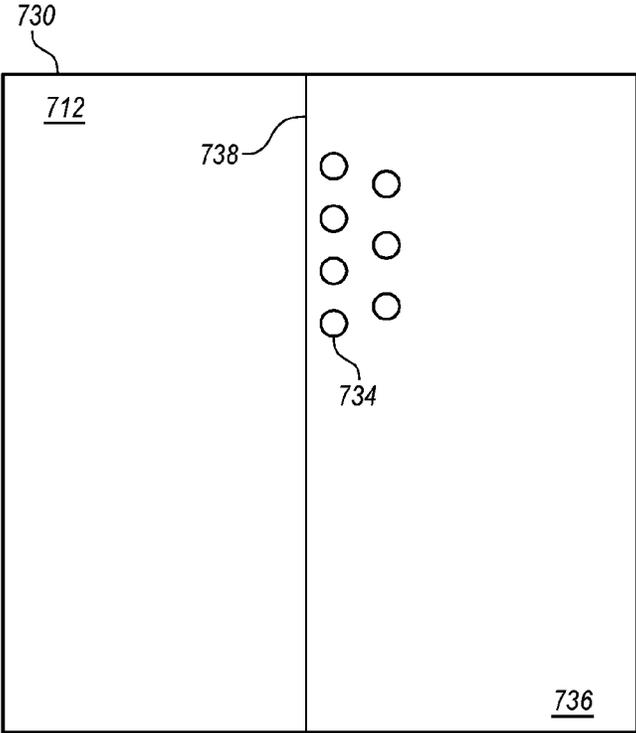


FIG. 7E

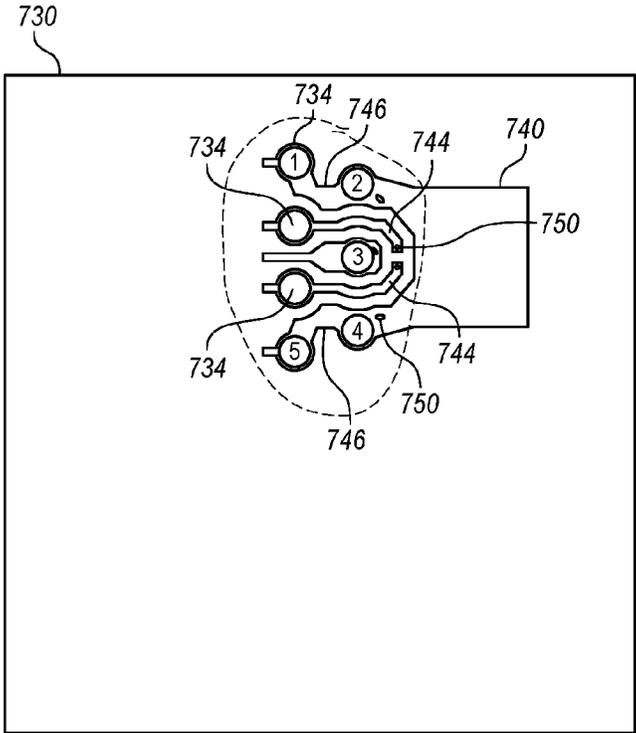


FIG. 7F

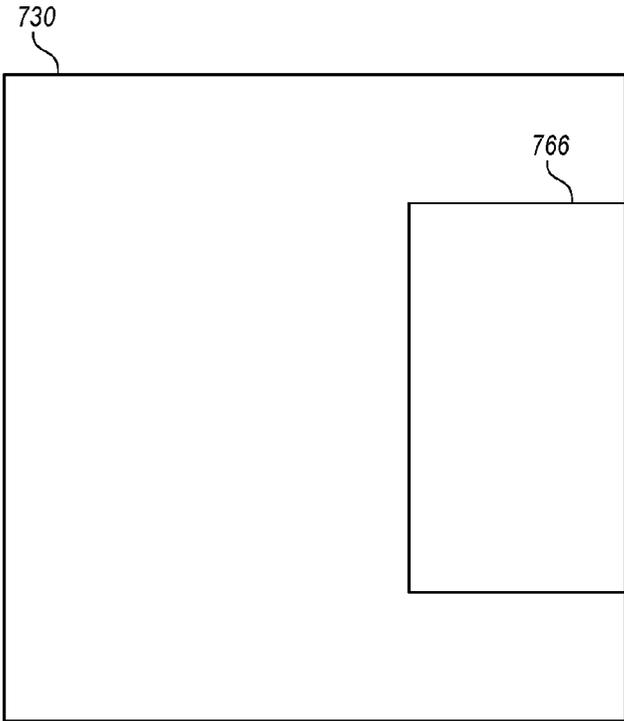


FIG. 7G

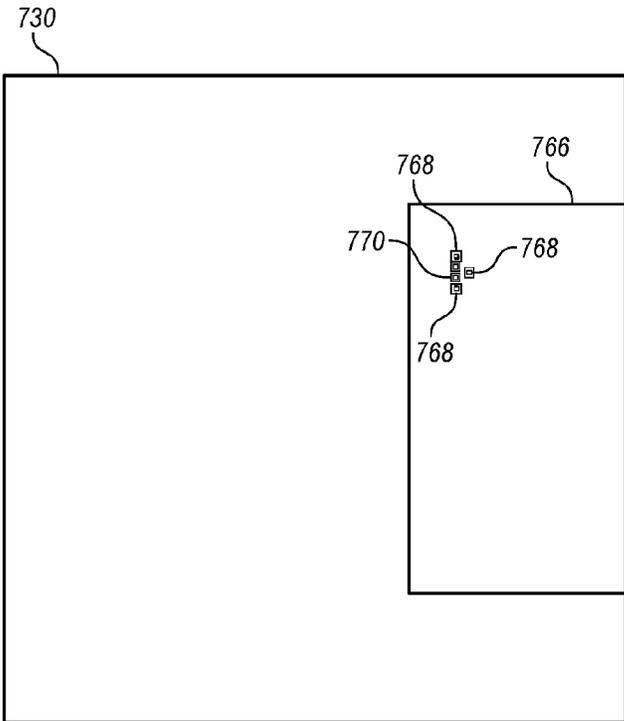


FIG. 7H

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ELECTRICAL INTERFACE FOR PRINTED CIRCUIT BOARD, PACKAGE AND DIE

FIELD OF THE INVENTION

The innovation relates to electrical connections between a printed circuit boards and a die and in particular to a novel layout for a printed circuit board to lead frame to die interface.

RELATED ART

Modern electronic circuits are contained on a die which is typically formed from a silicon wafer, but other materials or configuration are possible. The electronic circuits on the die perform the signal processing or other operations on the electrical signals as is understood in the art.

The die is typically contained within a package. The package surrounds the die and is formed from an insulating plastic, resin, or epoxy material. One or more pins extends outward from the package and the pins may be located on the sides or periphery of the package or on the bottom. An electrical connection must be made between the die and the pins of the package so that an electrical signal may be presented to the die and received from the die at the exterior of the package (or, presented to the package and received from the package at the die).

Supporting the package is a circuit board, which are common in the art. The circuit board is typically a multilayer structure of alternating insulating and conductive layers. The pins from the package connect to electrical conductors in the circuit board. The circuit board is then built to an electrical device, such as but not limited to communication equipment, computer devices, mobile communication devices, or any number of other devices that utilize electronic circuits.

One challenge and limiting factor to the advancement of circuit operation and data rates is the interface between the circuit board and the die. The path between the circuit board and the die can affect overall performance and be the limiting factor to performance.

The need was to create a low cost wire bonded package to achieve comparable electrical performance to a chip-scale package (CSP). While CSP has the advantage of not requiring bond wires which can impact and limit performance, CSP can suffer from other drawbacks—namely excess capacitive loading and hence system performance impairment. The issue with low cost wire-bonded packages (QFN or other technologies that use bond wires) is that it is difficult to achieve proper differential-mode and common-mode impedances in order to obtain desirable device-level return losses. The wire bonds also create bandwidth limitations that affect signal transmission, for example, rise/fall time and inter-symbol interference (ISI) jitter. In the design disclosed herein the bandwidth for the prior art configuration was limited in range from 20 GHz to 48 GHz depending on the application.

Prior solutions to overcome the drawbacks of the prior art typically optimize each segment individually and simply utilize known-configurations. The prior art does not address the interrelation between segments and does not account for modal transmission or propagation characteristics.

FIG. 1 illustrates an exemplary prior art conductor layout within a package for a circuit board to die interface. As shown, a die **104** is presented and asserted to include one or more electronic circuits (not shown). Around the die **104** is a package **120** (shown in cut away to aid in understanding). The package **120** includes conductive areas **116** and **124**,

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namely ground node **116** and signal paths **124**. The ground nodes electrically connect to the die **104** through one or more bond wires **108**. The signal paths electrically connect to the die **104** through one or more bond wires **110**. Also part of the package are ground pad **138** and signal path pad **130A**, **130B**. Through these pads **138**, **130A**, **130B** in connection with one or more vias and conductive traces of the circuit board, the die electrically connects to the circuit board.

This prior art configuration shown in FIG. 1 suffers from the drawbacks mentioned above including poor return paths to ground, inductive and capacitive coupling, limited bandwidth performance, phase distortion, and other performance limiting drawbacks. An additional drawback with prior art designs is that each segment is evaluated alone which leads to performance characteristics that neglect the overall collective performance behavior under all operating circumstances.

SUMMARY

To overcome the drawbacks of the prior art and provide additional benefits, an assembly is disclosed that comprises an arrangement of insulating material and conductive material configured to establish an electrical connection between a circuit board and a die. The disclosed designs were created to provide a cost effective manufacturable design that eliminates or minimizes differential-mode and common-mode mismatches along the transmission path made up of 1) die bond pads, 2) bond wires, 3) lead frame bond pads, 4) lead frame, 5) lead frame-to-pin transition, 6) pin-to-PCB transition, and 7) PCB transmission line.

In one embodiment, the assembly comprises a circuit board, a package and a die. The circuit board includes a circuit board conductive layer serving and configured as a ground plane, a circuit board insulating layer on the conductive layer, one or more ground vias electrically connected to the circuit board conductive layer, one or more signal solder pads on the insulating layer, one or more signal transmission lines formed from conductive material on the insulating layer such that the one or more signal transmission lines terminate at the one or more signal solder pads, and a circuit board ground pad electrically connected to two or more ground vias such that the two or more ground vias are electrically connected to the circuit board conductive layer. The ground pad has a concave shaped edge facing the one or more signal solder pads.

The package comprises an insulating material and conductive material. The package comprises two or more conductors exposed on a package exterior including at least one conductor comprising an exterior ground conductor and at least one conductor comprising an exterior signal conductor such that the exterior signal conductor is configured to electrically connect to at least one signal solder pad on the circuit board and the exterior ground conductor is configured to electrically connect to at least one ground via on the circuit board.

The package may further comprise a right hand side ground path electrically connected to the circuit board ground pad, a left hand side ground path electrically connected to the circuit board ground pad, a center ground path electrically connected to the circuit board ground pad, a first signal path between the right hand side ground path and the center ground path such that the first signal path connects at a first end to at least one signal transmission line of the circuit board and connects at a second end to a first bond wire, and a second signal path between the left hand side ground path and the center ground path such that the second

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signal path connected at a first end to at least one signal transmission line of the circuit board and connected at a second end to a second bond wire such that the first and second bond wires electrically connect to a die.

In one embodiment, a generally uniform distance is maintained between the left hand side ground path and the first signal path and a generally uniform distance is maintained between the right hand side ground path and the second signal path. In addition, a generally uniform distance may be maintained between the first signal path and the center ground path and a generally uniform distance may be maintained between the second signal path and the center ground path.

In this assembly, the first signal path and the second signal path may be traces having a uniform width. In addition, the ground bond wires electrically connect the die ground to the right hand side ground path, left hand side ground path, and center ground path. In one embodiment there are five ground vias extending upward through the circuit board and in alignment with exterior ground conductors exposed on a package exterior.

It is further contemplated that the one or more signal solder pads of the circuit board may comprise a first signal solder pad and second signal solder pad, the first signal solder pad electrically connects to the first signal path of the package and the second signal solder pad electrically connects to the second signal path of the package.

Disclosed herein is an assembly comprising an arrangement of insulating material and conductive material configured to establish an electrical connection between a circuit board and a die. In this embodiment, the assembly comprises a circuit board ground layer formed of conducting material and a circuit board insulating layer on the conductive layer. At least one signal transmission line terminating at and electrically connects to the at least one signal solder pad on the circuit board insulating layer. A circuit board ground pad electrically connects to the circuit board ground layer such that the ground pad has a concave shaped edge facing at least one signal solder pad. Also part of this embodiment is a package comprising insulating material and conductive material such that the package includes two or more package ground pads exposed on a package exterior electrically connected to the circuit board ground pad and one or more package signal pads exposed on a package exterior electrically connected to the signal solder pad. Within the package, there is at least a right hand side ground path electrically connected to at least one package ground pad and at least a left hand side ground path electrically connected to at least one package ground pad. A package signal path is between the right hand side ground path and the left hand side ground path such that the package signal path electrically connects at a first end to at least one package signal pad and electrically connects at a second end to a signal bond wire.

One embodiment further comprises a second package signal path within the package and a center ground path electrically connected to the right hand side ground path and the left hand side ground path such that the center ground path is located between the package signal path and second package signal path. The center ground path may have a bond wire attachment point to which a bond wire attaches, the right hand side ground path may have a bond wire attachment point to which a bond wire attaches, and the left hand side ground path may have a bond wire attachment point to which a bond wire attaches. In this embodiment, the distance between the center ground path and the package

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signal is generally uniform and a distance between the center ground path and the second package signal path may be generally uniform.

The two or more package ground pads on the exterior of the package are aligned above the circuit board ground pad such that the concave shaped edge faces at least one signal solder pad. In one embodiment, the package signal path and second package signal path have a generally uniform width along at least fifty percent of its length.

Also disclosed herein is a circuit board and package assembly configured to electrically connect a die to a circuit board. In this embodiment the assembly comprises a circuit board signal path on an insulating layer of the circuit board terminating in a signal pad and a ground pad on the insulating layer of the circuit board. The circuit board ground pad has a concave shaped side that forms a recess such that at least one signal pad is at least partially within the recess formed by the concave shaped side. A package is part of the assembly and is located on the circuit board such that two or more package ground pads align along the concave shaped side of the circuit board ground pad and at least one package signal pad is at least partially within the recess formed by the concave shaped side of the ground pad. The two or more package ground pads extend upward into the package to electrically connect to package ground paths and the at least one package signal pad extends upward into the package to electrically connect to a package signal path.

In one embodiment, the at least one package signal path extends from the package signal pad toward the die and has a generally constant width. The two or more package ground pads may consist of five package ground pads, all of which are contained within an area defined by the circuit board ground pad and electrically connect to the circuit board ground pad to form a ground return path of controlled characteristics. It is also contemplated that the assembly may include two circuit board signal paths, each connecting to a signal pad and also include two package signal pads which connect to a first package signal path and a second package signal path, both of the first package signal path and a second package signal path extend toward the die and a center ground pad on the circuit board which electrically connects to a center package ground pad, which electrically connects to a package center ground path.

In this embodiment the package center ground path is located between the first package signal path and a second package signal path. Furthermore, the package ground paths may comprise a first package ground path and a second package ground path, both of which extend toward the die, such that the first package signal path is between the first package ground path and the package center ground path and the second package signal path is between the second package ground path and the package center ground path. It is further contemplated that a distance between the first package signal path and the first package ground path is generally consistent as the first package signal path extends toward the die and a distance between the second package signal path and the second package ground path is generally consistent as the second package signal path extends toward the die.

Other systems, methods, features and advantages of the invention will be or will become apparent to one with skill in the art upon examination of the following figures and detailed description. It is intended that all such additional systems, methods, features and advantages be included

within this description, be within the scope of the invention, and be protected by the accompanying claims.

BRIEF DESCRIPTION OF THE DRAWINGS

The components in the figures are not necessarily to scale, emphasis instead being placed upon illustrating the principles of the invention. In the figures, like reference numerals designate corresponding parts throughout the different views.

FIG. 1 is a perspective view of a prior art package to die interface.

FIG. 2A is a plot of signal magnitude and a plot of return loss in differential mode in a prior art system at various frequencies.

FIG. 2B is a plot of signal magnitude and a plot of return loss in differential mode in a system embodied with the disclosed innovation at various frequencies.

FIG. 3A is a plot of return loss in common mode in a prior art system operating at various frequencies.

FIG. 3B is a plot of signal magnitude and a plot of return loss in common mode in a system embodied with the disclosed innovation operating at various frequencies.

FIG. 4 a top plan view of the circuit board, package, and die with associated electrical connectivity.

FIG. 5 is a side plan cut-away view of the circuit board, package, and die with associated electrical connectivity.

FIG. 6 is a perspective cut-away view of the circuit board, package, and die with associated electrical connectivity.

FIG. 7A illustrates a top view of a layer of the circuit board formed of conductive material.

FIG. 7B illustrates a top view of an additional layer of the circuit board formed of insulating material.

FIG. 7C illustrates a top view of an additional layer of the circuit board formed of conductive material.

FIG. 7D illustrates a bottom view of a layer of the package formed of conductive material.

FIG. 7E illustrates a bottom view of a layer of the package formed of insulating and conductive material.

FIG. 7F illustrates a top view of an additional layer of the package formed of conductive material.

FIG. 7G illustrates a view of a layer of the package and die formed of insulating material.

FIG. 7H illustrates a top view of a layer of the package and die formed of conductive material.

DETAILED DESCRIPTION

FIG. 2A is a plot of signal magnitude and a plot of return loss in differential mode in a prior art system at various frequencies. As shown in FIG. 2A, in the graph **200** the vertical axis **208** represents dB of signal loss while the horizontal axis **212** represents frequency in GHz. On the vertical axis a -3 dB point **216** is a relevant point for this discussion and may be used to define or compare system performance. A signal plot **202** is shown as plot **220**. This signal plot is -3 dB down in signal magnitude at about 40 GHz of signal frequency **224**. This is typical of prior art system performance.

Also shown in FIG. 2A is return loss plots **230A**, **230B** for differential mode operation. One plot is referenced looking into or toward the die from the circuit board while another of the plots is looking toward or into the circuit board from the die. As can be viewed from the return loss plots **230A**, **230B** for differential mode operation, the prior art systems suffer from significant return loss and the return loss behavior is inconsistent over the illustrated frequency range.

FIG. 2B is a plot of signal magnitude and a plot of return loss in differential mode in a system embodied with the disclosed innovation at various frequencies. As compared to FIG. 2A, similar elements are identified with similar reference numbers. As shown in FIG. 2B, in the graph **200** the vertical axis **208** represents dB of signal loss while the horizontal axis **212** represents frequency in GHz. In contrast to FIG. 2A, the plot of signal magnitude **258** is significantly better such that the -3 dB transition **216** [in signal magnitude is at or near 100 GHz **250**. This is a significant improvement in performance and enables operation at significantly higher frequencies.

Also shown in FIG. 2B is return loss plots **254A**, **254B**. One plot is referenced looking into or toward the die from the circuit board while another of the plots is looking from die into or toward package. As can be viewed from the return loss plots **230A**, **230B**, the system incorporating the disclosed innovation greatly improves performance in relation to return loss compared to the prior art system plots shown in FIG. 2A. The return loss plot **254A**, **254B** are better over the shown frequencies and do not suffer from significant variation.

FIG. 3A is a plot of return loss in common mode in a prior art system operating at various frequencies. As shown in FIG. 3A, in the graph **300** the vertical axis **308** represents dB of signal loss while the horizontal axis **312** represents frequency in GHz. Also shown in FIG. 3A is return loss plots **320**, **324** for common mode operation. Plot **320** is referenced looking into or toward the die from the circuit board while plot **324** is looking from the circuit board into or toward die. As can be viewed from the return loss plots **320**, **324** for common mode operation, the prior art system suffers from significant return loss and the return loss behavior is inconsistent and include numerous spikes over the illustrated frequency range.

FIG. 3B is a plot of signal magnitude and a plot of return loss in common mode in a system embodied with the disclosed innovation operating at various frequencies. As shown in FIG. 3B, in the graph **3020** the vertical axis **308** represents dB of signal loss while the horizontal axis **312** represents frequency in GHz. Also shown in FIG. 3B is return loss plots **350**, **354** for common mode operation. Plot **350** is referenced looking into or toward the die from the circuit board while plot **354** is looking from the circuit board into or toward the die. As can be viewed from the return loss plots **350**, **354** for common mode operation, the system incorporating the innovation disclosed herein has a significant improvement in return loss and the return loss behavior is more consistent and include fewer spikes over the illustrated frequency range as compared to the prior art plots shown in FIG. 3A.

FIG. 4 a top plan view of the circuit board, package, and die with associated electrical connectivity. FIG. 5 is a side plan cut-away view of the circuit board, package, and die with associated electrical connectivity. FIG. 6 is a perspective cut-away view of the circuit board, package, and die with associated electrical connectivity. FIGS. 4, 5, and 6 are jointly discussed below to avoid redundancy between elements which are generally similar but shown in different views. In general, FIGS. 4, 5, and 6 illustrate an electrical interface between a circuit board **404**, package **424**, and die **428**. This interface is a built-up three dimensional arrangement of insulating elements and conductive elements arranged to electrically interface the circuit board **404** to the die **428**.

As is commonly understood, a circuit board **404**, which may be a multi-layer printed circuit board, is composed of

various conductive and insulating layers. In this embodiment, a lower conductive layer **504** serves as a base layer. Above the lower conductive layer **504** is an insulating layer **508**. In turn, above insulating layer **508** is another conductive layer **512** which when combined with selective conductor location control and insulating material location control may be made to establish one or more signal transmission line **408** on the circuit board **404** and a ground plane **420**. As shown in FIG. 6, the signal transmission line **408** are part of the circuit board **404** and terminate at a signal via **440**. The signal transmission line **408** may operate in differential mode, common mode, or both, subject to other elements including the die and the components which connected to the circuit board **404**.

The signal transmission line **408** connects to the vias **440** which extended through the circuit board **404** to present a signal solder pad at the top of the circuit board. Subsequent figures illustrates the location of the signal solder pads in relation to the package. In this example embodiment the signal solder pads may be for use with a traditional package design with pins extending from the periphery of the package or arranged in an array for a flip chip configuration. Also part of the circuit board **404** is a ground path or ground plane that connects to ground vias **436**. The ground vias present an electrical connection from a ground path or ground plane from the circuit board to the package. As with the signal solder pads for the signal path, the ground connects are also presented to the upper level of the circuit board for connection to the package **428**.

Turning now to the package **424**, several electrical connections are provided to electrically connect the package to the die **428**. In general, there is a signal path and a ground path. With regard to the signal path, the circuit board transmission lines **408** connect to the package through conductive vias **440** and then to package signal paths **470**. Pads electrically connect the vias **440** to the package signal paths **470**. The package signal paths **470** extend toward the die **428** as shown and terminate near the die **428** and within connection distance to the die.

In addition to the signal paths **470**, ground nodes are provided which include outer ground node (paths) **444A**, located on each side of the signal paths **470** as shown, and an inner ground node (path) **444B** located between the signal paths **470**. Both the ground nodes **444A**, **444B**, and the signal paths **470** may comprise any type of conductive material. The ground nodes **444A** connect to outer ground vias **436** and solder pads (not shown) which extend through and upward from the circuit board **404**. A center (inner) ground node **444B** connects to an electrically conductive via **438**, which in turn connects to the lower ground plane **420**.

The lower ground plane **420** that extends outward from each via **436**, **438** to form a conductive ground plane as shown. The ground plane includes a concave arc **422** that opposes the two signal vias **440**. The concave side **420** of the ground extends to each side of the signal vias **440**. One or more ground vias **436** are located near the outer most portions of the ends of the concave arc.

Bond wire contact points are located generally near the die to which bond wires **460** connect to the package signal paths **470**. The opposing end of the bond wires **460** connect to bond wire pads on the die **428**. Although labeled with a single reference number **460**, the certain bond wires conduct the signal while others conduct or function as ground conductors. Bond wires **460** which connect to the signal path on the package **424** and die **428** are signal bond wires while bond wires which connect to ground paths on the package

and die are ground bond wires. Additional details regarding the bond wire **460** contact points are provided below.

Between the outer ground nodes **444A** and the signal path **470** is a space or void comprised of insulating material. An inner insulating section **454** is placed between inner ground node **444B** and the signal paths **470**. An outer insulating section **450** is provided between the signal path **470** and the outer ground nodes **444A**. As shown in this embodiment the arrangement is symmetric such that both sides of the inner ground node are mirrored images of the other. In other embodiments the arrangement may be non-symmetric. Further and as discussed herein, the performance improvements are based at least in part on the configuration shown but deviations may occur from this configuration without departing from the claims that follow. Deviations in configuration shape and layout which gain the benefits described herein are contemplated and should be considered as covered directly or by the doctrine of equivalents.

In this example embodiment, which was configured for simulation and manufacturing, the nature of the manufacturing process leaves tails **466** extending from the features of the design and in particular the ground nodes **444A**, **444B** and the package signal paths **470**. Element **416B** is a bond pad or connection pad between the vias **440** that extends upward from the lower levels of the package **424** and the signal transmission lines **408**.

FIG. 5 and FIG. 6 also illustrate the multiple tier bonding arrangement for the ground areas. As shown in FIG. 5, the top most bond wires **460** connect to a ground area, which in turn electrically connects to a lower tier ground area through the conductive vias **436**, **440**. One or more lower tiers may be connected in this manner. This is also shown in FIG. 6 such that the upper ground areas **444A**, **444B** connect to lower ground tiers through vias, such as vias **436**. Using two or more tiers with bonding to lower ground layers provides the benefit of flexibility to assign and arrange conductors to facilitate management of modal impedance characteristics within the constraints of technology and manufacturing design rules as well as for specific product needs.

The present design has several advantages over prior art systems. Present design is optimized and designed to meet specification for both common mode and differential mode behavior. Thus, the modal impedances are both optimized. As to the modality designed into the system, the design disclosed improves greatly upon prior art designs by better balancing modal impedances to achieve the lowest possible impedance variation for each of the major modes—differential and common modes. Achieving the lowest possible impedance variation manifests as improved bandwidth, improved return loss, and reduced signal distortion due to resonances caused by interaction of mismatches.

FIGS. 7A-7H illustrates the various layers of an exemplary embodiment of the circuit board, package, and die for the configuration described herein. This is but on one possible layer stack up. FIG. 7A illustrates a top view of a layer of the circuit board formed of conductive material. The area shown generally is a portion of the circuit board **700** which is a conductive layer **704** covering the circuit board while via locations **708** are shown as circles or other conductive access areas where the vias are located. The conductive layer **704** forms an RF ground layer. The circuit board **700** may be any type circuit board, such as a layered circuit board, printed circuit board, or other type of support structure. That circuit board **700** may be of any shape and the view shown in FIG. 7A is just a section of the overall board. The layer shown in FIG. 7A may be considered a base layer,

such that the other layers or elements shown in FIG. 7B-7H reside on top of the layer shown in FIG. 7A.

FIG. 7B illustrates a top view of an additional layer of the circuit board formed of insulating material. This insulating layer 712 is on top of the conductive layer 704 shown in FIG. 7A. Shown through the insulating layer 712 are the conductive via locations 708, which electrically connect to the conductive layer below and conductive layer above.

FIG. 7C illustrates a top view of an additional layer of the circuit board formed of conductive material. This layer includes the upper ground plane 716 that electrically connects to the via locations 708, which in turn connect to the conductive ground plane 704 shown in FIG. 7A. This layer also includes the signal transmission lines 720 which electrically connect to solder pads 722. The signal transmission lines 720 may be micro-strip lines. One skilled in the art may contemplate that if the signal transmission lines 720 were sandwiched between adjacent (above and below) ground planes, then stripline transmission lines would result. While the figures and illustrated embodiment do not detail this case, the case should be contemplated included and considered as covered by subsequent claims either directly or by the doctrine of equivalents. Returning to FIG. 7C, the features described reside atop the insulating layer 712 of the circuit board 700. The upper ground plan 716 may be referred to as a metal flood. As shown, the edge that faces or opposes the transmission lines solder pads 722 is concave to at least partially curve around the solder pads. In this embodiment there are seven vias that are part of the ground path but in other embodiments greater or fewer vias may be used. In this embodiment the ground vias 708 are located and spaced in a uniform manner in relation to the signal solder pads. Analogous to the description of multi-tiered bond wire use and arrangement, the placement of the ground pads and vias has the benefit of allowing management of modal impedance characteristics within the constraints of technology and manufacturing design rules as well as for specific product needs. It should be understood that the locations, dimensions, and quantity of connections may differ in other embodiments. However, all possible variations should be covered within the scope of claims and in particular following the pattern of forming a generally concave ground shape opposing the signals. Heat dissipation vias are used for heat dissipation from the die to the package to the circuit board and are not shown in this figure. The via locations are not limited to the locations shown.

FIG. 7D illustrates a bottom view of a layer of the package formed of conductive material. As shown, the package 730 has a bottom which is comprise primarily of insulating material 736 such as an epoxy overmold. The package pins 734 protrude from the package 730 as shown. The pin 734 may comprise solder bumps, pins, solder balls, or any other conductive feature on the package. FIG. 7E illustrates a bottom view of a layer of the package formed of insulating and conductive material. This view is generally similar to FIG. 7D, but the package edge 738 is shown imposed on top of the circuit board 712. In the present embodiment an array of pins are illustrated. In other embodiments the pins may reside along the package edge 738 in what is commonly known as a peripheral array of pins.

FIG. 7F illustrates a top view of an additional layer of the package formed of conductive material. This layer is one layer up within the package assembly and the sections shown are conductive layers. The package pins 734 of the package electrically connect to the conductors 746, 744 which are established as conductive areas of this layer. The package pins 1-5 are all part of a common ground which

includes package ground conductive areas 740 and conductive wings 746. The package ground conductive areas 740 electrically connects all the package grounds together. The signal package pins 734 are established within the package as shown such there is a signal path 744 which extends from the package pins 734 as shown. The signal pins may carry signals in differential mode or common mode. There is a uniform distance between the ground wings 746 and the signal paths 744. Between the signal paths 744 is a ground pin (3) with associated ground conductor established as shown. The ground pin (3) and the associated ground area that is located at a uniform distance from the signal paths 744 provides an important return path to ground for the signals. Presence of this ground allows adjustment of electro-magnetic coupling between the two signal paths 744 and hence allows adjustment of modal impedance within the package planar signal routing region. A uniform distance is maintained between the ground pin conductor and the signal paths 744. Also shown in FIG. 7F are the bond wire contact points 750. The bond wires (not shown) connect the package 730 to the die (not shown). Certain bond wires will electrically connect to the signal conductors 744 to the die while other bond wires will electrically connect the ground path 740, 746, and package pin (3) to the die. As a benefit to this arrangement, the size and distance of the arrangement shown may ratio up or down in size to accommodate other sizes of dies and/or other package technology design and manufacturing rules. The scaling may occur left to right or top to bottom and is contemplated that the scaling would also occur in the Z-axis.

FIG. 7G illustrates a view of a layer of the package and die. In this view the die 766 is on the package 730. FIG. 7H illustrates a top view of the die with die bond pad 768, 770. The bond pads 770 are for the signal path and the bond pads 768 connect the die to the ground conductor of the package. The dots at the center of each bond pad 768, 770 are bond wire contact points.

While various embodiments of the invention have been described, it will be apparent to those of ordinary skill in the art that many more embodiments and implementations are possible that are within the scope of this invention. In addition, the various features, elements, and embodiments described herein may be claimed or combined in any combination or arrangement.

What is claimed is:

1. An assembly comprising an arrangement of insulating material and conductive material configured to establish an electrical connection between a circuit board to a die, the assembly comprising:

- a circuit board comprising:
 - a circuit board conductive layer serving configured as a ground plane;
 - an circuit board insulating layer on the conductive layer;
 - one or more ground vias electrically connected to the circuit board conductive layer;
 - one or more signal solder pads on the insulating layer;
 - one or more signal transmission lines formed from conductive material on the insulating layer, the one or more signal transmission lines terminating at the one or more signal solder pads;
 - a circuit board ground pad electrically connected to two or more ground vias, the two or more ground vias electrically connected to the circuit board conductive layer, the ground pad having a generally concave shaped edge facing the one or more signal solder pads;

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- a package comprising insulating material and conductive material, the package comprising:
- two or more conductors exposed on a package exterior, at least one conductor comprising an exterior ground conductor and at least one conductor comprising an exterior signal conductor such that the exterior signal conductor is configured to electrically connect to at least one signal solder pad on the circuit board and the exterior ground conductor is configured to electrically connect to at least one ground vias on the circuit board.
2. The assembly of claim 1 further comprising:
- a right hand side ground path electrically connected to the circuit board ground pad;
 - a left hand side ground path electrically connected to the circuit board ground pad;
 - a center ground path electrically connected to the circuit board ground pad;
 - a first signal path between the right hand side ground path and the center ground path, the first signal path connected at a first end to at least one signal transmission line of the circuit board and connected at a second end to a first bond wire;
 - a second signal path between the left hand side ground path and the center ground path, the second signal path connected at a first end to at least one signal transmission line of the circuit board and connected at a second end to a second bond wire, the first and second bond wires electrically connecting to a die.
3. The assembly of claim 2 wherein a generally uniform distance is maintained between the left hand side ground path and the first signal path and a generally uniform distance is maintained between the right hand side ground path and the second signal path.
4. The assembly of claim 3 wherein a generally uniform distance is maintained between the first signal path and the center ground path and a generally uniform distance is maintained between the second signal path and the center ground path.
5. The assembly of claim 2 wherein the first signal path and the second signal path are traces having a uniform width.
6. The assembly of claim 1 wherein ground bond wires electrically connect the die ground to the right hand side ground path, left hand side ground path, and center ground path.
7. The assembly of claim 1 wherein there are five or more ground vias extending upward through the circuit board and in alignment with exterior ground conductors exposed on a package exterior.
8. The assembly of claim 1 wherein the one or more signal solder pads of the circuit board comprise a first signal solder pad and second signal solder pad, the first signal solder pad electrically connects to the first signal path of the package and the second signal solder pad electrically connects to the second signal path of the package.
9. An assembly comprising an arrangement of insulating material and conductive material configured to establish an electrical connection between a circuit board and a die, the assembly comprising:
- a circuit board comprising:
 - a circuit board ground layer formed of conducting material;
 - a circuit board insulating layer on the conductive layer;
 - at least one signal transmission line terminating at and electrically connect to at least one signal solder pad on the circuit board insulating layer;

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- a circuit board ground pad electrically connected to the circuit board ground layer the ground pad having a generally concave shaped edge facing at least one signal solder pads;
- a package comprising insulating material and conductive material, the package comprising:
- two or more package ground pads exposed on a package exterior electrically connected to the circuit board ground pad;
 - one or more package signal pads exposed on a package exterior electrically connected to the signal solder pad; and
 - within the package, at least a right hand side ground path electrically connected to at least one package ground pad and left hand side ground path electrically connected to at least one package ground pad;
 - a package signal path between the right hand side ground path and the left hand side ground path, the package signal path electrically connected at a first end to at least one package signal pad and electrically connected at a second end to signal bond wire.
10. The assembly of claim 9 further comprising a second package signal path within the package and a center ground path electrically connected to the right hand side ground path and the left hand side ground path, the center ground path electrically connected to the right hand side ground path and the left hand side ground path and located between the package signal path and second package signal path.
11. The assembly of claim 10 wherein the center ground path has a bond wire attachment point to which a bond wire attaches, the right hand side ground path has a bond wire attachment point to which a bond wire attaches, and the left hand side ground path has a bond wire attachment point to which a bond wire attaches.
12. The assembly of claim 10 wherein a distance between the center ground path and the package signal and is generally uniform and a distance between the center ground path and the second package signal path is generally uniform.
13. The assembly of claim 9 wherein the two or more package ground pads on the exterior of the package are aligned above the circuit board ground pad such that the generally concave shaped edge faces at least one signal solder pads.
14. The assembly of claim 9 wherein the package signal path and second package signal path has a generally uniform width along at least fifty percent of its length.
15. A circuit board and package assembly configured to electrically connect a die to a circuit board, the assembly comprising:
- a circuit board signal path on an insulating layer of the circuit board terminating in a signal pad;
 - a ground pad on the insulating layer of the circuit board, the circuit board ground pad having a generally concave shaped side that forms a recess such that at least one signal pad is at least partially within the recess formed by the concave shaped side;
 - a package located on the circuit board such that two or more package ground pad align along the concave shaped side of the circuit board ground pad and at least one package signal pad is at least partially within the recess formed by the concave shaped side of the ground pad, the two or more package ground pads extending upward into the package to electrically connect to package ground to paths and the at least one package signal pad extending upward into the package to electrically connect to a package signal path.

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16. The assembly of claim 15 wherein the at least one package signal path extends from the package signal pad toward the die and has a generally constant width.

17. The assembly of claim 15 wherein the two or more package ground pads consists of five package ground pads, all of which are contained within an area defined by the circuit board ground pad and electrically connect to the circuit board ground pad to form an RF signal reference and ground return path.

18. The assembly of claim 15 wherein the assembly includes two circuit board signal paths, each connecting to a signal pad and two package signal pads which connect to a first package signal path and a second package signal path, both of the first package signal path and a second package signal path extending toward the die; and

a center ground pad on the circuit board which electrically connects to a center package ground pad, which electrically connects to a package center ground path, the

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package center ground path located between the first package signal path and a second package signal path.

19. The assembly of claim 18 wherein the package ground paths comprise a first package ground path and a second package ground path, both of which extend toward the die, such that the first package signal path is between the first package ground path and the package center ground path and the second package signal path is between the second package ground path and the package center ground path.

20. The assembly of claim 19 wherein a distance between the first package signal path and the first package ground path is generally consistent as the first package signal path extends toward the die and a distance between the second package signal path and the second package ground path is generally consistent as the second package signal path extends toward the die.

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